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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	26
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	1.5K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12g48f1clcr

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### 1.3.8 System Integrity Support

- Power-on reset (POR)
- System reset generation
- Illegal address detection with reset
- Low-voltage detection with interrupt or reset
- Real time interrupt (RTI)
- Computer operating properly (COP) watchdog
  - Configurable as window COP for enhanced failure detection
  - Initialized out of reset using option bits located in flash memory
- Clock monitor supervising the correct function of the oscillator

### 1.3.9 Timer (TIM)

- Up to eight x 16-bit channels for input capture or output compare
- 16-bit free-running counter with 7-bit precision prescaler
- In case of eight channel timer Version an additional 16-bit pulse accumulator is available

### 1.3.10 Pulse Width Modulation Module (PWM)

- Up to eight channel x 8-bit or up to four channel x 16-bit pulse width modulator
  - Programmable period and duty cycle per channel
  - Center-aligned or left-aligned outputs
  - Programmable clock select logic with a wide range of frequencies

# 1.3.11 Controller Area Network Module (MSCAN)

- 1 Mbit per second, CAN 2.0 A, B software compatible
  - Standard and extended data frames
  - 0–8 bytes data length
  - Programmable bit rate up to 1 Mbps
- Five receive buffers with FIFO storage scheme
- Three transmit buffers with internal prioritization
- Flexible identifier acceptance filter programmable as:
  - 2 x 32-bit
  - 4 x 16-bit
  - 8 x 8-bit
- Wakeup with integrated low pass filter option
- Loop back for self test
- Listen-only mode to monitor CAN bus

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Table 1-27. 64-Pin LQFP Pinout for S12G192 and S12G240

		<lowest< th=""><th>Function -PRIORITY-</th><th>highest</th><th>&gt;</th><th>Power</th><th colspan="4"></th></lowest<>	Function -PRIORITY-	highest	>	Power				
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func	Supply	CTRL	Reset State		
28	PT4	IOC4	_	_	_	V <sub>DDX</sub>	PERT/PPST	Disabled		
29	PT3	IOC3	_	_	_	V <sub>DDX</sub>	PERT/PPST	Disabled		
30	PT2	IOC2	_	_	_	V <sub>DDX</sub>	PERT/PPST	Disabled		
31	PT1	IOC1	ĪRQ	_	_	V <sub>DDX</sub>	PERT/PPST	Disabled		
32	PT0	IOC0	XIRQ	_	_	V <sub>DDX</sub>	PERT/PPST	Disabled		
33	PAD0	KWAD0	AN0	_	_	V <sub>DDA</sub>	PER1AD/PPS1AD	Disabled		
34	PAD8	KWAD8	AN8	_	_	V <sub>DDA</sub>	PER0AD/PPS0AD	Disabled		
35	PAD1	KWAD1	AN1	_	_	V <sub>DDA</sub>	PER1AD/PPS1AD	Disabled		
36	PAD9	KWAD9	AN9	_	_	$V_{DDA}$	PER0ADPPS0AD	Disabled		
37	PAD2	KWAD2	AN2	_	_	V <sub>DDA</sub>	PER1AD/PPS1AD	Disabled		
38	PAD10	KWAD10	AN10	_	_	V <sub>DDA</sub>	PER0AD/PPS0AD	Disabled		
39	PAD3	KWAD3	AN3	_	_	V <sub>DDA</sub>	PER1AD/PPS1AD	Disabled		
40	PAD11	KWAD11	AN11	_	_	V <sub>DDA</sub>	PER0AD/PPS0AD	Disabled		
41	PAD4	KWAD4	AN4	_	_	$V_{DDA}$	PER1AD/PPS1AD	Disabled		
42	PAD12	KWAD12	AN12	_	_	$V_{DDA}$	PER0AD/PPS0AD	Disabled		
43	PAD5	KWAD5	AN5		_	$V_{DDA}$	PER1AD/PPS1AD	Disabled		
44	PAD13	KWAD13	AN13		_	$V_{DDA}$	PER0AD/PPS0AD	Disabled		
45	PAD6	KWAD6	AN6	_	_	$V_{DDA}$	PER1AD/PPS1AD	Disabled		
46	PAD14	KWAD14	AN14	_	_	$V_{DDA}$	PER0AD/PPS0AD	Disabled		
47	PAD7	KWAD7	AN7		_	$V_{DDA}$	PER1AD/PPS1AD	Disabled		
48	PAD15	KWAD15	AN15		_	V <sub>DDA</sub>	PER0AD/PPS0AD	Disabled		
49	VRH	_	_	_	_	_	_	_		
50	VDDA	_	_	_	_	_	_	_		
51	VSSA	_	_	_	_	_	_	_		
52	PS0	RXD0	_	_	_	V <sub>DDX</sub>	PERS/PPSS	Up		
53	PS1	TXD0	_	_	_	V <sub>DDX</sub>	PERS/PPSS	Up		
54	PS2	RXD1	_	_	_	V <sub>DDX</sub>	PERS/PPSS	Up		
55	PS3	TXD1	_	_	_	V <sub>DDX</sub>	PERS/PPSS	Up		
56	PS4	MISO0	_	_	_	V <sub>DDX</sub>	PERS/PPSS	Up		

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Table 1-28. 100-Pin LQFP Pinout for S12G192 and S12G240

	< 0	Fund owestPRIO		st>	Power	Internal Pull Resistor			
Package Pin	Pin	2nd Func.	3rd Func.	4th Func.	Supply	CTRL	Reset State		
86	PS4	MISO0	_	_	$V_{DDX}$	PERS/PPSS	Up		
87	PS5	MOSI0	_	_	$V_{DDX}$	PERS/PPSS	Up		
88	PS6	SCK0	_	_	$V_{DDX}$	PERS/PPSS	Up		
89	PS7	API_EXTC LK	SS0	_	V <sub>DDX</sub>	PERS/PPSS	Up		
90	VSSX2	_	_	_	_	<del>_</del>	_		
91	VDDX2	_	_	_	_	_	_		
92	PM0	RXCAN	_	_	$V_{DDX}$	PERM/PPSM	Disabled		
93	PM1	TXCAN	_	_	$V_{DDX}$	PERM/PPSM	Disabled		
94	PD4	_	_	_	$V_{DDX}$	PUCR/PUPDE	Disabled		
95	PD5	_	_	_	$V_{DDX}$	PUCR/PUPDE	Disabled		
96	PD6	_	_	_	$V_{DDX}$	PUCR/PUPDE	Disabled		
97	PD7	_	_	_	$V_{DDX}$	PUCR/PUPDE	Disabled		
98	PM2	RXD2	_	_	$V_{DDX}$	PERM/PPSM	Disabled		
99	PM3	TXD2	_	_	$V_{DDX}$	PERM/PPSM	Disabled		
100	PJ7	KWJ7	SS2	_	$V_{DDX}$	PERJ/PPSJ	Up		

<sup>&</sup>lt;sup>1</sup> The regular I/O characteristics (see Section A.2, "I/O Characteristics") apply if the EXTAL/XTAL function is disabled

#### Port Integration Module (S12GPIMV1)

This section describes the signals available on each pin.

Although trying to enable multiple signals on a shared pin is not a proper use case in most applications, the resulting pin function will be determined by a predefined priority scheme as defined in 2.2.2 and 2.2.3.

Only enabled signals arbitrate for the pin and the highest priority defines its data direction and output value if used as output. Signals with programmable routing options are assumed to select the appropriate target pin to participate in the arbitration.

The priority is represented for each pin with shared signals from highest to lowest in the following format:

```
SignalA > SignalB > GPO
```

Here SignalA has priority over SignalB and general-purpose output function (GPO; represented by related port data register bit). The general-purpose output is always of lowest priority if no other signal is enabled.

Peripheral input signals on shared pins are always connected monitoring the pin level independent of their use.

**Table 3-2. ACMPC Register Field Descriptions (continued)** 

Field	Description
5 ACICE	ACMP Input Capture Enable— Establishes internal link to a timer input capture channel. When enabled, the associated timer pin is disconnected from the timer input. Refer to ACE description to account for initialization delay on this path.
	0 Timer link disabled 1 ACMP output connected to input capture channel 5
4 ACDIEN	ACMP Digital Input Buffer Enable— Enables the input buffers on ACMPP and ACMPM for the pins to be used with digital functions.
	<b>Note:</b> If this bit is set while simultaneously using the pin as an analog port, there is potentially increased power consumption because the digital input buffer may be in the linear region.
	0 Input buffers disabled on ACMPP and ACMPM 1 Input buffers enabled on ACMPP and ACMPM
3-2 ACMOD [1:0]	ACMP Mode— Selects the type of compare event setting ACIF.
	00 Flag setting disabled 01 Comparator output rising edge 10 Comparator output falling edge 11 Comparator output rising or falling edge
0 ACE	ACMP Enable— This bit enables the ACMP module and takes it into normal mode (see Section 3.5, "Modes of Operation"). This bit also connects the related input pins with the module's low pass input filters. When the module is not enabled, it remains in low power shutdown mode.
	Note: After setting ACE=1 an initialization delay of 63 bus clock cycles must be accounted for. During this time the comparator output path to all subsequent logic (ACO, ACIF, timer link, excl. ACMPO) is held at its current state. When resetting ACE to 0 the current state of the comparator will be maintained.
	0 ACMP disabled 1 ACMP enabled

# 3.6.2.2 ACMP Status Register (ACMPS)

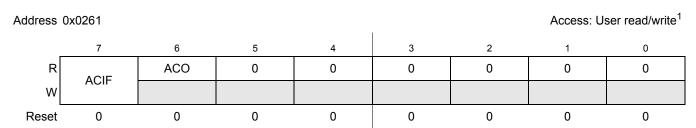


Figure 3-4. ACMP Status Register (ACMPS)

ACIF: Anytime, write 1 to clear

ACO: Never

Read: Anytime Write:

Analog-to-Digital Converter (ADC10B12CV2)

### 13.3.2 Register Descriptions

This section describes in address order all the ADC10B12C registers and their individual bits.

### 13.3.2.1 ATD Control Register 0 (ATDCTL0)

Writes to this register will abort current conversion sequence.

Module Base + 0x0000

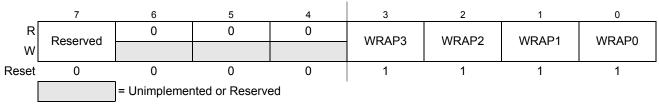


Figure 13-3. ATD Control Register 0 (ATDCTL0)

Read: Anytime

Write: Anytime, in special modes always write 0 to Reserved Bit 7.

Table 13-1. ATDCTL0 Field Descriptions

Field	Description
	<b>Wrap Around Channel Select Bits</b> — These bits determine the channel for wrap around when doing multi-channel conversions. The coding is summarized in Table 13-2.

Table 13-2. Multi-Channel Wrap Around Coding

WRAP3	WRAP2	WRAP1	WRAP0	Multiple Channel Conversions (MULT = 1) Wraparound to AN0 after Converting
0	0	0	0	Reserved <sup>1</sup>
0	0	0	1	AN1
0	0	1	0	AN2
0	0	1	1	AN3
0	1	0	0	AN4
0	1	0	1	AN5
0	1	1	0	AN6
0	1	1	1	AN7
1	0	0	0	AN8
1	0	0	1	AN9
1	0	1	0	AN10
1	0	1	1	AN11
1	1	0	0	AN11
1	1	0	1	AN11
1	1	1	0	AN11
1	1	1	1	AN11

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Address	Name	_	Bit 7	6	5	4	3	2	1	Bit 0
0x0003	ATDCTL3	R W	DJM	S8C	S4C	S2C	S1C	FIFO	FRZ1	FRZ0
0x0004	ATDCTL4	R W	SMP2	SMP1	SMP0	PRS[4:0]				
0x0005	ATDCTL5	R W	0	SC	SCAN	MULT	CD	CC	СВ	CA
0x0006	ATDSTAT0	R W	SCF	0	ETORF	FIFOR	CC3	CC2	CC1	CC0
0x0007	Unimple- mented	R W	0	0	0	0	0	0	0	0
0x0008	ATDCMPEH	R W	0	0	0	0		CMPE	[11:8]	
0x0009	ATDCMPEL	R W				CM	PE[7:0]			
0x000A	ATDSTAT2H	R W	0	0	0	0		CCF	[11:8]	
0x000B	ATDSTAT2L	R W				CC	F[7:0]			
0x000C	ATDDIENH	R W	1	1	1	1		IEN[	11:8]	
0x000D	ATDDIENL	R W				IE	l N[7:0]			
0x000E	ATDCMPHTH	R W	0	0	0	0		СМРН	T[11:8]	
0x000F	ATDCMPHTL	R W				L CMF	 PHT[7:0]			
0x0010	ATDDR0	R W						esult Data (Data (		
0x0012	ATDDR1	R W		See S	Section 14.3	.2.12.1, "Let	ft Justified Re	esult Data (Data (	JM=0)"	
0x0014	ATDDR2	R W		See S	Section 14.3	.2.12.1, "Let	ft Justified Re	esult Data (Data (	JM=0)"	
0x0016	ATDDR3	R W		See S	Section 14.3	.2.12.1, "Let	ft Justified Re	esult Data (Data (	JM=0)"	
0x0018	ATDDR4	R W		See S	Section 14.3	.2.12.1, "Let	ft Justified Re	esult Data (D	JM=0)"	
0x001A	ATDDR5	R W		and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"  See Section 14.3.2.12.1, "Left Justified Result Data (DJM=0)"						
0x001C	ATDDR6	R W	and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"  See Section 14.3.2.12.1, "Left Justified Result Data (DJM=0)"  and Section 14.3.2.12.3, "Right Justified Result Data (DJM=1)"							
0x001E	ATDDR7	R W	and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"  See Section 14.3.2.12.1, "Left Justified Result Data (DJM=0)"  and Section 14.3.2.12.2, "Pight Justified Result Data (DJM=1)"							
0x0020	ATDDR8	R W	and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"  See Section 14.3.2.12.1, "Left Justified Result Data (DJM=0)"  and Section 14.3.2.12.2, "Pight Justified Result Data (DJM=1)"							
0x0022	ATDDR9	R W	and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"  See Section 14.3.2.12.1, "Left Justified Result Data (DJM=0)"  and Section 14.3.2.12.2, "Right Justified Result Data (DJM=1)"							
		۱ ۷۷		1	mented or R		oddinod IV	Data (L	1)	

Figure 14-2. ADC12B12C Register Summary (Sheet 2 of 3)

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**Table 14-16. ATDSTAT0 Field Descriptions (continued)** 

Field	Description
3–0 CC[3:0]	Conversion Counter — These 4 read-only bits are the binary value of the conversion counter. The conversion counter points to the result register that will receive the result of the current conversion. E.g. CC3=0, CC2=1, CC1=1, CC0=0 indicates that the result of the current conversion will be in ATD Result Register 6. If in non-FIFO mode (FIFO=0) the conversion counter is initialized to zero at the beginning and end of the conversion sequence. If in FIFO mode (FIFO=1) the register counter is not initialized. The conversion counter wraps around when its maximum value is reached.  Aborting a conversion or starting a new conversion clears the conversion counter even if FIFO=1.

# 14.3.2.8 ATD Compare Enable Register (ATDCMPE)

Writes to this register will abort current conversion sequence.

Read: Anytime Write: Anytime

Module Base + 0x0008

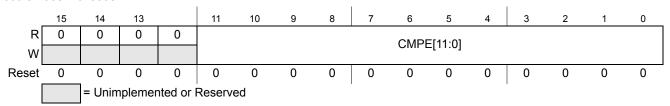


Figure 14-10. ATD Compare Enable Register (ATDCMPE)

**Table 14-17. ATDCMPE Field Descriptions** 

Field	Description
11-0 CMPE[11:0]	Compare Enable for Conversion Number $n$ ( $n$ = 11, 10, 9, 8, 7, 6, 5, 4, 3, 2, 1, 0) of a Sequence ( $n$ conversion number, NOT channel number!) — These bits enable automatic compare of conversion results individually for conversions of a sequence. The sense of each comparison is determined by the CMPHT[ $n$ ] bit in the ATDCMPHT register.
	For each conversion number with CMPE[ <i>n</i> ]=1 do the following:  1) Write compare value to ATDDR <i>n</i> result register  2) Write compare operator with CMPHT[ <i>n</i> ] in ATDCPMHT register
	CCF[ <i>n</i> ] in ATDSTAT2 register will flag individual success of any comparison.  0 No automatic compare  1 Automatic compare of results for conversion <i>n</i> of a sequence is enabled.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0	
0x0007	R	0	0	0	0	0	0	0	0	
RESERVED	W									
0x0008 PWMSCLA	R W	Bit 7	6	5	4	3	2	1	Bit 0	
0x0009 PWMSCLB	R W	Bit 7	6	5	4	3	2	1	Bit 0	
0x000A	R	0	0	0	0	0	0	0	0	
RESERVED	W									
0x000B RESERVED	R	0	0	0	0	0	0	0	0	
KESEKVED	W									
0x000C PWMCNT0 <sup>2</sup>	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCN10-	W	0	0	0	0	0	0	0	0	
0x000D	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT1 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x000E	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT2 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x000F	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT3 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x0010	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT4 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x0011	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT5 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x0012	R	Bit 7	6	5	4	3	2	1	Bit 0	
PWMCNT6 <sup>2</sup>	W	0	0	0	0	0	0	0	0	
0x0013 PWMCNT7 <sup>2</sup>	R	Bit 7	6	5	4	3	2	1	Bit 0	
	W	0	0	0	0	0	0	0	0	
0x0014 PWMPER0 <sup>2</sup>	R W	Bit 7	6	5	4	3	2	1	Bit 0	
0x0015 PWMPER1 <sup>2</sup>	R W	Bit 7	6	5	4	3	2	1	Bit 0	
			= Unimplemented or Reserved							

Figure 19-2. The scalable PWM Register Summary (Sheet 1 of 4)

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Timer Module (TIM16B8CV3)

#### 25.4.4.2.1 Define FCCOB Contents

The FCCOB parameter fields must be loaded with all required parameters for the Flash command being executed. Access to the FCCOB parameter fields is controlled via the CCOBIX bits in the FCCOBIX register (see Section 25.3.2.3).

The contents of the FCCOB parameter fields are transferred to the Memory Controller when the user clears the CCIF command completion flag in the FSTAT register (writing 1 clears the CCIF to 0). The CCIF flag will remain clear until the Flash command has completed. Upon completion, the Memory Controller will return CCIF to 1 and the FCCOB register will be used to communicate any results. The flow for a generic command write sequence is shown in Figure 25-26.

Table 26-46. Erase Flash Block Command FCCOB Requirements

CCOBIX[2:0]	FCCOB P	arameters				
000	0x09	Global address [17:16] to identify Flash block				
001	Global address [15:0] in	Global address [15:0] in Flash block to be erased				

Upon clearing CCIF to launch the Erase Flash Block command, the Memory Controller will erase the selected Flash block and verify that it is erased. The CCIF flag will set after the Erase Flash Block operation has completed.

Table 26-47. Erase Flash Block Command Error Handling

Register	Error Bit	Error Condition		
		Set if CCOBIX[2:0] != 001 at command launch		
		Set if command not available in current mode (see Table 26-27)		
	ACCERR	Set if an invalid global address [17:16] is supplied		
FSTAT		Set if the supplied P-Flash address is not phrase-aligned or if the EEPROM address is not word-aligned		
	FPVIOL	Set if an area of the selected Flash block is protected		
	MGSTAT1 Set if any errors have been encountered during the verify operation			
	MGSTAT0	Set if any non-correctable errors have been encountered during the verify operation		

#### 26.4.6.9 Erase P-Flash Sector Command

The Erase P-Flash Sector operation will erase all addresses in a P-Flash sector.

Table 26-48. Erase P-Flash Sector Command FCCOB Requirements

CCOBIX[2:0]	FCCOB Parameters				
000	0x0A	Global address [17:16] to identify P-Flash block to be erased			
001	Global address [15:0] anywhere within the sector to be erased.  Refer to Section 26.1.2.1 for the P-Flash sector size.				

Upon clearing CCIF to launch the Erase P-Flash Sector command, the Memory Controller will erase the selected Flash sector and then verify that it is erased. The CCIF flag will be set after the Erase P-Flash Sector operation has completed.

#### **27.4.8** Wait Mode

The Flash module is not affected if the MCU enters wait mode. The Flash module can recover the MCU from wait via the CCIF interrupt (see Section 27.4.7, "Interrupts").

#### **27.4.9** Stop Mode

If a Flash command is active (CCIF = 0) when the MCU requests stop mode, the current Flash operation will be completed before the MCU is allowed to enter stop mode.

### 27.5 Security

The Flash module provides security information to the MCU. The Flash security state is defined by the SEC bits of the FSEC register (see Table 27-11). During reset, the Flash module initializes the FSEC register using data read from the security byte of the Flash configuration field at global address 0x3\_FF0F. The security state out of reset can be permanently changed by programming the security byte assuming that the MCU is starting from a mode where the necessary P-Flash erase and program commands are available and that the upper region of the P-Flash is unprotected. If the Flash security byte is successfully programmed, its new value will take affect after the next MCU reset.

The following subsections describe these security-related subjects:

- Unsecuring the MCU using Backdoor Key Access
- Unsecuring the MCU in Special Single Chip Mode using BDM
- Mode and Security Effects on Flash Command Availability

# 27.5.1 Unsecuring the MCU using Backdoor Key Access

The MCU may be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor keys (four 16-bit words programmed at addresses 0x3\_FF00-0x3\_FF07). If the KEYEN[1:0] bits are in the enabled state (see Section 27.3.2.2), the Verify Backdoor Access Key command (see Section 27.4.6.11) allows the user to present four prospective keys for comparison to the keys stored in the Flash memory via the Memory Controller. If the keys presented in the Verify Backdoor Access Key command match the backdoor keys stored in the Flash memory, the SEC bits in the FSEC register (see Table 27-11) will be changed to unsecure the MCU. Key values of 0x0000 and 0xFFFF are not permitted as backdoor keys. While the Verify Backdoor Access Key command is active, P-Flash memory and EEPROM memory will not be available for read access and will return invalid data.

#### 28.4.6.11 Verify Backdoor Access Key Command

The Verify Backdoor Access Key command will only execute if it is enabled by the KEYEN bits in the FSEC register (see Table 28-10). The Verify Backdoor Access Key command releases security if user-supplied keys match those stored in the Flash security bytes of the Flash configuration field (see Table 28-4). The Verify Backdoor Access Key command must not be executed from the Flash block containing the backdoor comparison key to avoid code runaway.

CCOBIX[2:0]	FCCOB Parameters					
000	0x0C	Not required				
001	Key 0					
010	Key 1					
011	Ke	y 2				
100	Ke	y 3				

Table 28-52. Verify Backdoor Access Key Command FCCOB Requirements

Upon clearing CCIF to launch the Verify Backdoor Access Key command, the Memory Controller will check the FSEC KEYEN bits to verify that this command is enabled. If not enabled, the Memory Controller sets the ACCERR bit in the FSTAT register and terminates. If the command is enabled, the Memory Controller compares the key provided in FCCOB to the backdoor comparison key in the Flash configuration field with Key 0 compared to 0x3\_FF00, etc. If the backdoor keys match, security will be released. If the backdoor keys do not match, security is not released and all future attempts to execute the Verify Backdoor Access Key command are aborted (set ACCERR) until a reset occurs. The CCIF flag is set after the Verify Backdoor Access Key operation has completed.

Register	Error Bit	Error Condition
		Set if CCOBIX[2:0] != 100 at command launch
		Set if an incorrect backdoor key is supplied
	ACCERR	Set if backdoor key access has not been enabled (KEYEN[1:0] != 10, see Section 28.3.2.2)
FSTAT		Set if the backdoor key has mismatched since the last reset
	FPVIOL	None
	MGSTAT1	None
	MGSTAT0	None

Table 28-53. Verify Backdoor Access Key Command Error Handling

# 28.4.6.12 Set User Margin Level Command

The Set User Margin Level command causes the Memory Controller to set the margin level for future read operations of the P-Flash or EEPROM block.

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Address & Name		7	6	5	4	3	2	1	0
0x000A FCCOBHI	R W	CCOB15	CCOB14	CCOB13	CCOB12	CCOB11	CCOB10	ССОВ9	CCOB8
0x000B FCCOBLO	R W	CCOB7	CCOB6	CCOB5	CCOB4	CCOB3	CCOB2	CCOB1	ССОВ0
0x000C	R	0	0	0	0	0	0	0	0
FRSV1	W								
0x000D	R	0	0	0	0	0	0	0	0
FRSV2	W								
0x000E	R	0	0	0	0	0	0	0	0
FRSV3	W								
0x000F	R	0	0	0	0	0	0	0	0
FRSV4	W								
0x0010	R	NV7	NV6	NV5	NV4	NV3	NV2	NV1	NV0
FOPT	W								
0x0011	R	0	0	0	0	0	0	0	0
FRSV5	W								
0x0012	R	0	0	0	0	0	0	0	0
FRSV6	W								
0x0013	R	0	0	0	0	0	0	0	0
FRSV7	W								
			= Unimplemented or Reserved						

Figure 30-4. FTMRG192K2 Register Summary (continued)

# 30.3.2.1 Flash Clock Divider Register (FCLKDIV)

The FCLKDIV register is used to control timed events in program and erase algorithms.

Table 30-13. FCNFG Field Descriptions

Field	Description
7 CCIE	Command Complete Interrupt Enable — The CCIE bit controls interrupt generation when a Flash command has completed.  0 Command complete interrupt disabled  1 An interrupt will be requested whenever the CCIF flag in the FSTAT register is set (see Section 30.3.2.7)
4 IGNSF	Ignore Single Bit Fault — The IGNSF controls single bit fault reporting in the FERSTAT register (see Section 30.3.2.8).  O All single bit faults detected during array reads are reported  Single bit faults detected during array reads are not reported and the single bit fault interrupt will not be generated
1 FDFD	Force Double Bit Fault Detect — The FDFD bit allows the user to simulate a double bit fault during Flash array read operations and check the associated interrupt routine. The FDFD bit is cleared by writing a 0 to FDFD.  O Flash array read operations will set the DFDIF flag in the FERSTAT register only if a double bit fault is detected  Any Flash array read operation will force the DFDIF flag in the FERSTAT register to be set (see Section 30.3.2.7) and an interrupt will be generated as long as the DFDIE interrupt enable in the FERCNFG register is set (see Section 30.3.2.6)
0 FSFD	Force Single Bit Fault Detect — The FSFD bit allows the user to simulate a single bit fault during Flash array read operations and check the associated interrupt routine. The FSFD bit is cleared by writing a 0 to FSFD.  0 Flash array read operations will set the SFDIF flag in the FERSTAT register only if a single bit fault is detected 1 Flash array read operation will force the SFDIF flag in the FERSTAT register to be set (see Section 30.3.2.7) and an interrupt will be generated as long as the SFDIE interrupt enable in the FERCNFG register is set (see Section 30.3.2.6)

### 30.3.2.6 Flash Error Configuration Register (FERCNFG)

The FERCNFG register enables the Flash error interrupts for the FERSTAT flags.

Offset Module Base + 0x0005

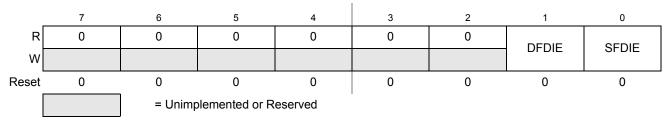


Figure 30-10. Flash Error Configuration Register (FERCNFG)

All assigned bits in the FERCNFG register are readable and writable.

#### **NOTE**

Vector addresses and their relative interrupt priority are determined at the MCU level.

#### 30.4.7.1 Description of Flash Interrupt Operation

The Flash module uses the CCIF flag in combination with the CCIE interrupt enable bit to generate the Flash command interrupt request. The Flash module uses the DFDIF and SFDIF flags in combination with the DFDIE and SFDIE interrupt enable bits to generate the Flash error interrupt request. For a detailed description of the register bits involved, refer to Section 30.3.2.5, "Flash Configuration Register (FCNFG)", Section 30.3.2.6, "Flash Error Configuration Register (FERCNFG)", Section 30.3.2.7, "Flash Status Register (FSTAT)", and Section 30.3.2.8, "Flash Error Status Register (FERSTAT)".

The logic used for generating the Flash module interrupts is shown in Figure 30-27.

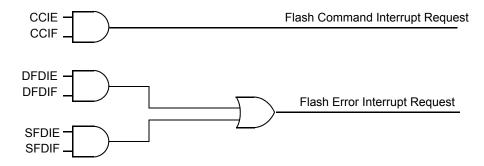


Figure 30-27. Flash Module Interrupts Implementation

#### **30.4.8 Wait Mode**

The Flash module is not affected if the MCU enters wait mode. The Flash module can recover the MCU from wait via the CCIF interrupt (see Section 30.4.7, "Interrupts").

# **30.4.9** Stop Mode

If a Flash command is active (CCIF = 0) when the MCU requests stop mode, the current Flash operation will be completed before the MCU is allowed to enter stop mode.

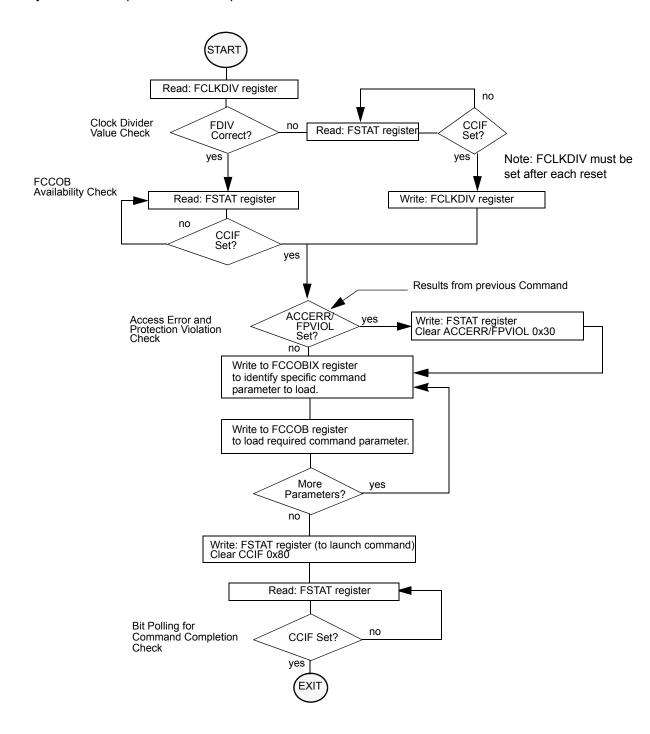


Figure 31-26. Generic Flash Command Write Sequence Flowchart

Table A-39. NVM Reliability Characteristics

Conditions are shown in Table A-4 unless otherwise noted								
NUM	С	Rating	Symbol	Min	Тур	Max	Unit	
		Program Flash Arrays						
1	С	Data retention at an average junction temperature of $T_{Javg}$ = 85°C <sup>1</sup> after up to 10,000 program/erase cycles	t <sub>NVMRET</sub>	20	100 <sup>2</sup>		Years	
2a	С	Program Flash number of program/erase cycles (-40°C $\leq$ Tj $\leq$ 150°C)	n <sub>FLPE</sub>	10K	100K <sup>3</sup>	_	Cycles	
2b	С	Program Flash number of program/erase cycles (150°C $\leq$ Tj $\leq$ 160°C)	n <sub>FLPE</sub>	1K	100K <sup>3</sup>	_	Cycles	
		EEPROM Array						
3	С	Data retention at an average junction temperature of $T_{Javg}$ = 85°C <sup>1</sup> after up to 100,000 program/erase cycles	t <sub>NVMRET</sub>	5	100 <sup>2</sup>	_	Years	
4	С	Data retention at an average junction temperature of $T_{Javg} = 85^{\circ}C^{1}$ after up to 10,000 program/erase cycles	t <sub>NVMRET</sub>	10	100 <sup>2</sup>	_	Years	
5	С	Data retention at an average junction temperature of T <sub>Javg</sub> = 85°C <sup>1</sup> after less than 100 program/erase cycles	t <sub>NVMRET</sub>	20	100 <sup>2</sup>	_	Years	
6a	С	EEPROM number of program/erase cycles (-40°C $\leq$ Tj $\leq$ 150°C)	n <sub>FLPE</sub>	100K	500K <sup>3</sup>	_	Cycles	
6b	С	EEPROM number of program/erase cycles (150°C $\leq$ Tj $\leq$ 160°C)	n <sub>FLPE</sub>	10K	500K <sup>3</sup>	_	Cycles	

<sup>&</sup>lt;sup>1</sup> T<sub>Javg</sub> does not exceed 85°C in a typical temperature profile over the lifetime of a consumer, industrial or automotive application.

# A.8 Phase Locked Loop

#### A.8.1 Jitter Definitions

With each transition of the feedback clock, the deviation from the reference clock is measured and input voltage to the VCO is adjusted accordingly. The adjustment is done continuously with no abrupt changes in the VCOCLK frequency. Noise, voltage, temperature and other factors cause slight variations in the control loop resulting in a clock jitter. This jitter affects the real minimum and maximum clock periods as illustrated in Figure A-4.

Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how NXP defines Typical Data Retention, please refer to Engineering Bulletin EB618

<sup>&</sup>lt;sup>3</sup> Spec table quotes typical endurance evaluated at 25°C for this product family. For additional information on how NXP defines Typical Endurance, please refer to Engineering Bulletin EB619.